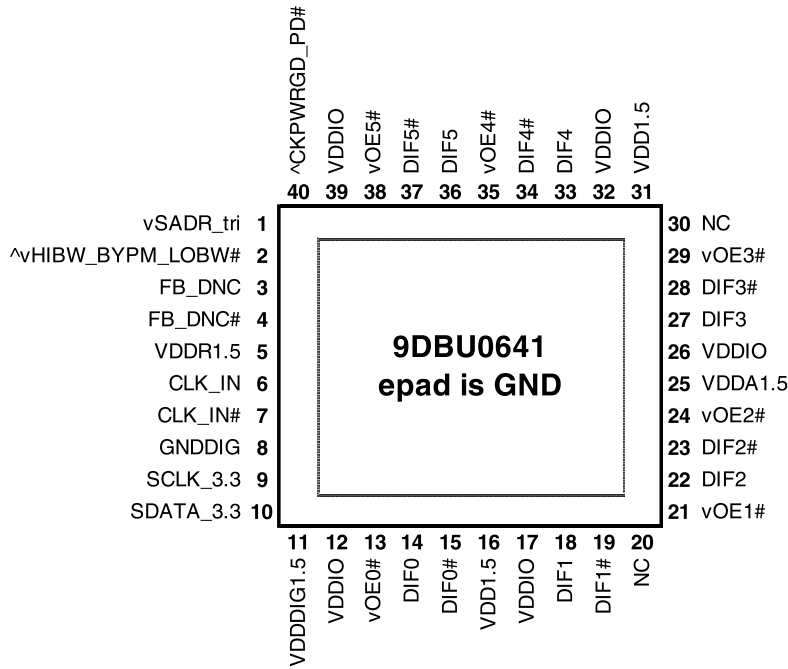




## Pin Configuration



40-VFQFPN, 5mm x 5mm 0.4mm pin pitch

^ prefix indicates internal 120KOhm pull up resistor

^v prefix indicates internal 120KOhm pull up AND pull down resistor (biased to VDD/2)

v prefix indicates internal 120KOhm pull down resistor

### SMBus Address Selection Table

	SADR	Address	+ Read/Write bit
State of SADR on first application of CKPWRGD_PD#	0	1101011	x
	M	1101100	x
	1	1101101	x

### Power Management Table

CKPWRGD_PD#	CLK_IN	SMBus OEx bit	OEx# Pin	DIFx		PLL
				True O/P	Comp. O/P	
0	X	X	X	Low	Low	Off
1	Running	0	X	Low	Low	On <sup>1</sup>
1	Running	1	0	Running	Running	On <sup>1</sup>
1	Running	1	1	Low	Low	On <sup>1</sup>

1. If Bypass mode is selected, the PLL will be off, and outputs will follow this table.

### Power Connections

Pin Number			Description
VDD	VDDIO	GND	
5		41	Input receiver analog
11		8	Digital Power
16, 31	12, 17, 26, 32, 39	41	DIF outputs, Logic
25		41	PLL Analog

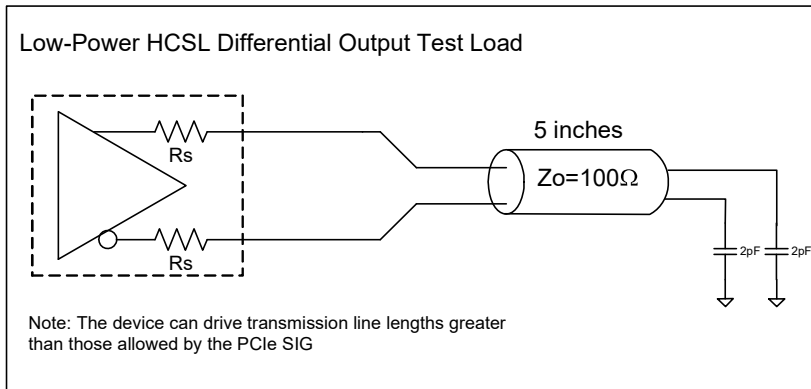
### PLL Operating Mode

HiBW_BypM_LoBW#	MODE	Byte1 [7:6] Readback	Byte1 [4:3] Control
0	PLL Lo BW	00	00
M	Bypass	01	01
1	PLL Hi BW	11	11

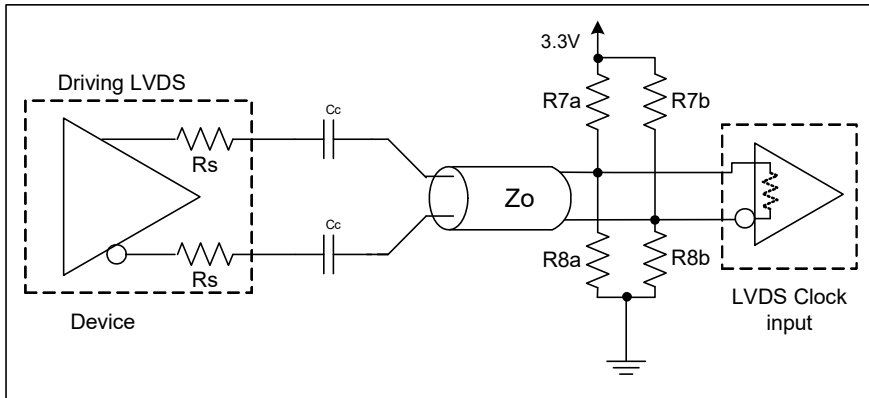
## Pin Descriptions

PIN #	PIN NAME	PIN TYPE	DESCRIPTION
1	vSADR_tri	LATCHED IN	Tri-level latch to select SMBus Address. See SMBus Address Selection Table.
2	^vHIBW_BYPM_LOBW#	LATCHED IN	Trilevel input to select High BW, Bypass or Low BW mode. See PLL Operating Mode Table for Details.
3	FB_DNC	DNC	True clock of differential feedback. The feedback output and feedback input are connected internally on this pin. Do not connect anything to this pin.
4	FB_DNC#	DNC	Complement clock of differential feedback. The feedback output and feedback input are connected internally on this pin. Do not connect anything to this pin.
5	VDDR1.5	PWR	1.5V power for differential input clock (receiver). This VDD should be treated as an Analog power rail and filtered appropriately.
6	CLK_IN	IN	True Input for differential reference clock.
7	CLK_IN#	IN	Complementary Input for differential reference clock.
8	GNDDIG	GND	Ground pin for digital circuitry
9	SCLK_3.3	IN	Clock pin of SMBus circuitry, 3.3V tolerant.
10	SDATA_3.3	I/O	Data pin for SMBus circuitry, 3.3V tolerant.
11	VDDDIG1.5	PWR	1.5V digital power (dirty power)
12	VDDIO	PWR	Power supply for differential outputs
13	vOE0#	IN	Active low input for enabling DIF pair 0. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
14	DIF0	OUT	Differential true clock output
15	DIF0#	OUT	Differential Complementary clock output
16	VDD1.5	PWR	Power supply, nominally 1.5V
17	VDDIO	PWR	Power supply for differential outputs
18	DIF1	OUT	Differential true clock output
19	DIF1#	OUT	Differential Complementary clock output
20	NC	N/A	No Connection.
21	vOE1#	IN	Active low input for enabling DIF pair 1. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
22	DIF2	OUT	Differential true clock output
23	DIF2#	OUT	Differential Complementary clock output
24	vOE2#	IN	Active low input for enabling DIF pair 2. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
25	VDDA1.5	PWR	1.5V power for the PLL core.
26	VDDIO	PWR	Power supply for differential outputs
27	DIF3	OUT	Differential true clock output
28	DIF3#	OUT	Differential Complementary clock output
29	vOE3#	IN	Active low input for enabling DIF pair 3. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
30	NC	N/A	No Connection.
31	VDD1.5	PWR	Power supply, nominally 1.5V
32	VDDIO	PWR	Power supply for differential outputs
33	DIF4	OUT	Differential true clock output
34	DIF4#	OUT	Differential Complementary clock output
35	vOE4#	IN	Active low input for enabling DIF pair 4. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
36	DIF5	OUT	Differential true clock output
37	DIF5#	OUT	Differential Complementary clock output
38	vOE5#	IN	Active low input for enabling DIF pair 5. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
39	VDDIO	PWR	Power supply for differential outputs
40	^CKPWRGD_PD#	IN	Input notifies device to sample latched inputs and start up on first high assertion. Low enters Power Down Mode, subsequent high assertions exit Power Down Mode. This pin has internal pull-up resistor.
41	ePAD	GND	Connect paddle to ground.

## Test Loads



## Driving LVDS



### Driving LVDS inputs

Component	Value		Note
	Receiver has termination	Receiver does not have termination	
R7a, R7b	10K ohm	140 ohm	
R8a, R8b	5.6K ohm	75 ohm	
Cc	0.1 uF	0.1 uF	
Vcm	1.2 volts	1.2 volts	

## Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 9DBU0641. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Supply Voltage	VDDx		-0.5		2	V	1,2
Input Voltage	V <sub>IN</sub>		-0.5		V <sub>DD</sub> +0.5	V	1,3
Input High Voltage, SMBus	V <sub>IHSMB</sub>	SMBus clock and data pins			3.3	V	1
Storage Temperature	T <sub>s</sub>		-65		150	°C	1
Junction Temperature	T <sub>j</sub>				125	°C	1
Input ESD protection	ESD prot	Human Body Model	2000			V	1

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup>Operation under these conditions is neither implied nor guaranteed.

<sup>3</sup>Not to exceed 2.0V.

## Electrical Characteristics–Clock Input Parameters

TA = T<sub>AMB</sub>, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input Common Mode Voltage - DIF_IN	V <sub>COM</sub>	Common Mode Input Voltage	200		725	mV	1
Input Swing - DIF_IN	V <sub>SWING</sub>	Differential value	300		1450	mV	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4		8	V/ns	1,2
Input Leakage Current	I <sub>IN</sub>	V <sub>IN</sub> = V <sub>DD</sub> , V <sub>IN</sub> = GND	-5		5	uA	
Input Duty Cycle	d <sub>tin</sub>	Measurement from differential waveform	45	50	55	%	1
Input Jitter - Cycle to Cycle	J <sub>DIFIn</sub>	Differential Measurement	0		150	ps	1

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup> Slew rate measured through +/-75mV window centered around differential zero

## Electrical Characteristics–Input/Supply/Common Parameters–Normal Operating Conditions

TA = T<sub>AMB</sub>; Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Supply Voltage	VDDx	Supply voltage for core and analog	1.425	1.5	1.575	V	
Output Supply Voltage	VDDIO	Supply voltage for Low Power HCSSL Outputs	0.95	1.05-1.5	1.575	V	
Ambient Operating Temperature	T <sub>AMB</sub>	Commercial range	0	25	70	°C	1
		Industrial range	-40	25	85	°C	1
Input High Voltage	V <sub>IH</sub>	Single-ended inputs, except SMBus	0.75 V <sub>DD</sub>		V <sub>DD</sub> + 0.3	V	
Input Mid Voltage	V <sub>IM</sub>	Single-ended tri-level inputs ('_tri' suffix)	0.4 V <sub>DD</sub>		0.6 V <sub>DD</sub>	V	
Input Low Voltage	V <sub>IL</sub>	Single-ended inputs, except SMBus	-0.3		0.25 V <sub>DD</sub>	V	
Input Current	I <sub>IN</sub>	Single-ended inputs, V <sub>IN</sub> = GND, V <sub>IN</sub> = VDD	-5		5	uA	
	I <sub>INP</sub>	Single-ended inputs V <sub>IN</sub> = 0 V; Inputs with internal pull-up resistors V <sub>IN</sub> = VDD; Inputs with internal pull-down resistors	-200		200	uA	
Input Frequency	F <sub>ibyp</sub>	Bypass mode	1		167	MHz	2
	F <sub>ipll</sub>	100MHz PLL mode	20	100.00	110	MHz	2
Pin Inductance	L <sub>pin</sub>				7	nH	1
Capacitance	C <sub>IN</sub>	Logic Inputs, except DIF_IN	1.5		5	pF	1
	C <sub>INDIF_IN</sub>	DIF_IN differential clock inputs	1.5		2.7	pF	1,5
	C <sub>OUT</sub>	Output pin capacitance			6	pF	1
Clk Stabilization	T <sub>STAB</sub>	From V <sub>DD</sub> Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock			1	ms	1,2
Input SS Modulation Frequency PCIe	f <sub>MODINPCIe</sub>	Allowable Frequency for PCIe Applications (Triangular Modulation)	30		33	kHz	
Input SS Modulation Frequency non-PCIe	f <sub>MODIN</sub>	Allowable Frequency for non-PCIe Applications (Triangular Modulation)	0		66	kHz	
OE# Latency	t <sub>LATOE#</sub>	DIF start after OE# assertion DIF stop after OE# deassertion	1		3	clocks	1,3
Tdrive_PD#	t <sub>DRVPD</sub>	DIF output enable after PD# de-assertion			300	us	1,3
Tfall	t <sub>F</sub>	Fall time of single-ended control inputs			5	ns	2
Trise	t <sub>R</sub>	Rise time of single-ended control inputs			5	ns	2
SMBus Input Low Voltage	V <sub>ILSMB</sub>				0.6	V	
SMBus Input High Voltage	V <sub>IHSMB</sub>	V <sub>DDSMB</sub> = 3.3V, see note 4 for V <sub>DDSMB</sub> < 3.3V	2.1		3.3	V	4
SMBus Output Low Voltage	V <sub>OLSMB</sub>	@ I <sub>PULLUP</sub>			0.4	V	
SMBus Sink Current	I <sub>PULLUP</sub>	@ V <sub>OL</sub>	4			mA	
Nominal Bus Voltage	V <sub>DDSMB</sub>	Bus Voltage	1.425		3.3	V	
SCLK/SDATA Rise Time	t <sub>RSMB</sub>	(Max V <sub>IL</sub> - 0.15) to (Min V <sub>IH</sub> + 0.15)			1000	ns	1
SCLK/SDATA Fall Time	t <sub>FSMB</sub>	(Min V <sub>IH</sub> + 0.15) to (Max V <sub>IL</sub> - 0.15)			300	ns	1
SMBus Operating Frequency	f <sub>MAXSMB</sub>	Maximum SMBus operating frequency			400	kHz	6

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup>Control input must be monotonic from 20% to 80% of input swing.

<sup>3</sup>Time from deassertion until outputs are >200 mV

<sup>4</sup> For V<sub>DDSMB</sub> < 3.3V, V<sub>IHSMB</sub> ≥ 0.8xV<sub>DDSMB</sub>

<sup>5</sup>DIF\_IN input

<sup>6</sup>The differential input clock must be running for the SMBus to be active

## Electrical Characteristics–DIF Low-Power HCSL Outputs

TA = T<sub>AMB</sub>; Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	dV/dt	Scope averaging on, fast setting (100MHz)	1	2.4	3.5	V/ns	1,2,3
	dV/dt	Scope averaging on, slow setting (100MHz)	0.7	1.7	2.5	V/ns	1,2,3
Slew rate matching	$\Delta$ dV/dt	Slew rate matching, Scope averaging on		9	20	%	1,2,4
Voltage High	V <sub>HIGH</sub>	Statistical measurement on single-ended signal using oscilloscope math function. (Scope averaging on)	630	750	850	mV	7
Voltage Low	V <sub>LOW</sub>		-150	26	150		7
Max Voltage	V <sub>max</sub>	Measurement on single ended signal using absolute value. (Scope averaging off)		763	1150	mV	7
Min Voltage	V <sub>min</sub>		-300	22			7
Vswing	Vswing	Scope averaging off	300	1448		mV	1,2
Crossing Voltage (abs)	V <sub>cross_abs</sub>	Scope averaging off	250	390	550	mV	1,5
Crossing Voltage (var)	$\Delta$ -V <sub>cross</sub>	Scope averaging off		11	140	mV	1,6

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup> Measured from differential waveform

<sup>3</sup> Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

<sup>4</sup> Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

<sup>5</sup> V<sub>cross</sub> is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

<sup>6</sup> The total variation of all V<sub>cross</sub> measurements in any particular system. Note that this is a subset of V<sub>cross\_min/max</sub> (V<sub>cross</sub> absolute) allowed. The intent is to limit V<sub>cross</sub> induced modulation by setting  $\Delta$ -V<sub>cross</sub> to be smaller than V<sub>cross</sub> absolute.

<sup>7</sup> At default SMBus settings.

## Electrical Characteristics–Current Consumption

TA = T<sub>AMB</sub>; Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Operating Supply Current	I <sub>DDA</sub>	VDDA+VDDR, PLL Mode, @100MHz		10.0	15	mA	1
	I <sub>DD</sub>	VDD, All outputs active @100MHz		4.5	8	mA	1
	I <sub>DDO</sub>	VDDIO, All outputs active @100MHz		25	31	mA	1
Powerdown Current	I <sub>DDAPD</sub>	VDDA+VDDR, CKPWRGD_PD#=0		0.5	1	mA	1, 2
	I <sub>DDPD</sub>	VDDx, CKPWRGD_PD#=0		0.2	0.5	mA	1, 2
	I <sub>DDOPD</sub>	VDDIO, CKPWRGD_PD#=0		0.0003	0.01	mA	1, 2

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup> Input clock stopped.

## Electrical Characteristics–Output Duty Cycle, Jitter, Skew and PLL Characteristics

TA = T<sub>AMB</sub>; Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
PLL Bandwidth	BW	-3dB point in High BW Mode (100MHz)	2.3	3.6	4.7	MHz	1,5
		-3dB point in Low BW Mode (100MHz)	1	1.6	2.5	MHz	1,5
PLL Jitter Peaking	t <sub>JPEAK</sub>	Peak Pass band Gain (100MHz)		1.3	2.5	dB	1
Duty Cycle	t <sub>DC</sub>	Measured differentially, PLL Mode	45	50	55	%	1
Duty Cycle Distortion	t <sub>DCD</sub>	Measured differentially, Bypass Mode @100MHz	-1	-0.6	0	%	1,3
Skew, Input to Output	t <sub>pdBYP</sub>	Bypass Mode, V <sub>T</sub> = 50%	3400	4301	5200	ps	1
	t <sub>pdPLL</sub>	PLL Mode V <sub>T</sub> = 50%	0	50	150	ps	1,4
Skew, Output to Output	t <sub>sk3</sub>	V <sub>T</sub> = 50%		37	75	ps	1,4
Jitter, Cycle to cycle	t <sub>jcy-cyc</sub>	PLL mode		24	50	ps	1,2
		Additive Jitter in Bypass Mode		0.1	25	ps	1,2

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup> Measured from differential waveform

<sup>3</sup> Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.

<sup>4</sup> All outputs at default slew rate

<sup>5</sup> The MIN/TYP/MAX values of each BW setting track each other, i.e., Low BW MAX will never occur with Hi BW MIN.

## Electrical Characteristics–Phase Jitter Parameters

TA = T<sub>AMB</sub>; Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	INDUSTRY LIMIT	UNITS	Notes
Phase Jitter, PLL Mode	t <sub>jphPCleG1</sub>	PCIe Gen 1		30	58	86	ps (p-p)	1,2,3,5
	t <sub>jphPCleG2</sub>	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		0.9	1.4	3	ps (rms)	1,2,3,5
		PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		2.1	2.6	3.1	ps (rms)	1,2,3,5
	t <sub>jphPCleG3</sub>	PCIe Gen 3 Common Clock Architecture (PLL BW of 2-4 or 2-5MHz, CDR = 10MHz)		0.5	0.6	1	ps (rms)	1,2,3,5
	t <sub>jphPCleG3SRns</sub>	PCIe Gen 3 Separate Reference No Spread (SRnS) (PLL BW of 2-4 or 2-5MHz, CDR = 10MHz)		0.5	0.6	0.7	ps (rms)	1,2,3,5
Additive Phase Jitter, Bypass Mode	t <sub>jphPCleG1</sub>	PCIe Gen 1		0.1	5	N/A	ps (p-p)	1,2,3,5
	t <sub>jphPCleG2</sub>	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		0.1	0.5	N/A	ps (rms)	1,2,3,4,5
		PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		0.1	0.3	N/A	ps (rms)	1,2,3,4
	t <sub>jphPCleG3</sub>	PCIe Gen 3 (PLL BW of 2-4 or 2-5MHz, CDR = 10MHz)		0.2	0.3	N/A	ps (rms)	1,2,3,4
	t <sub>jph125M0</sub>	125MHz, 1.5MHz to 10MHz, -20dB/decade rollover < 1.5MHz, -40db/decade rolloff > 10MHz		200	300	N/A	fs (rms)	1,6
t <sub>jph125M1</sub>	125MHz, 12KHz to 20MHz, -20dB/decade rollover < 1.5MHz, -40db/decade rolloff > 10MHz		313	350	N/A	fs (rms)	1,6	

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup> See <http://www.pcisig.com> for complete specs

<sup>3</sup> Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

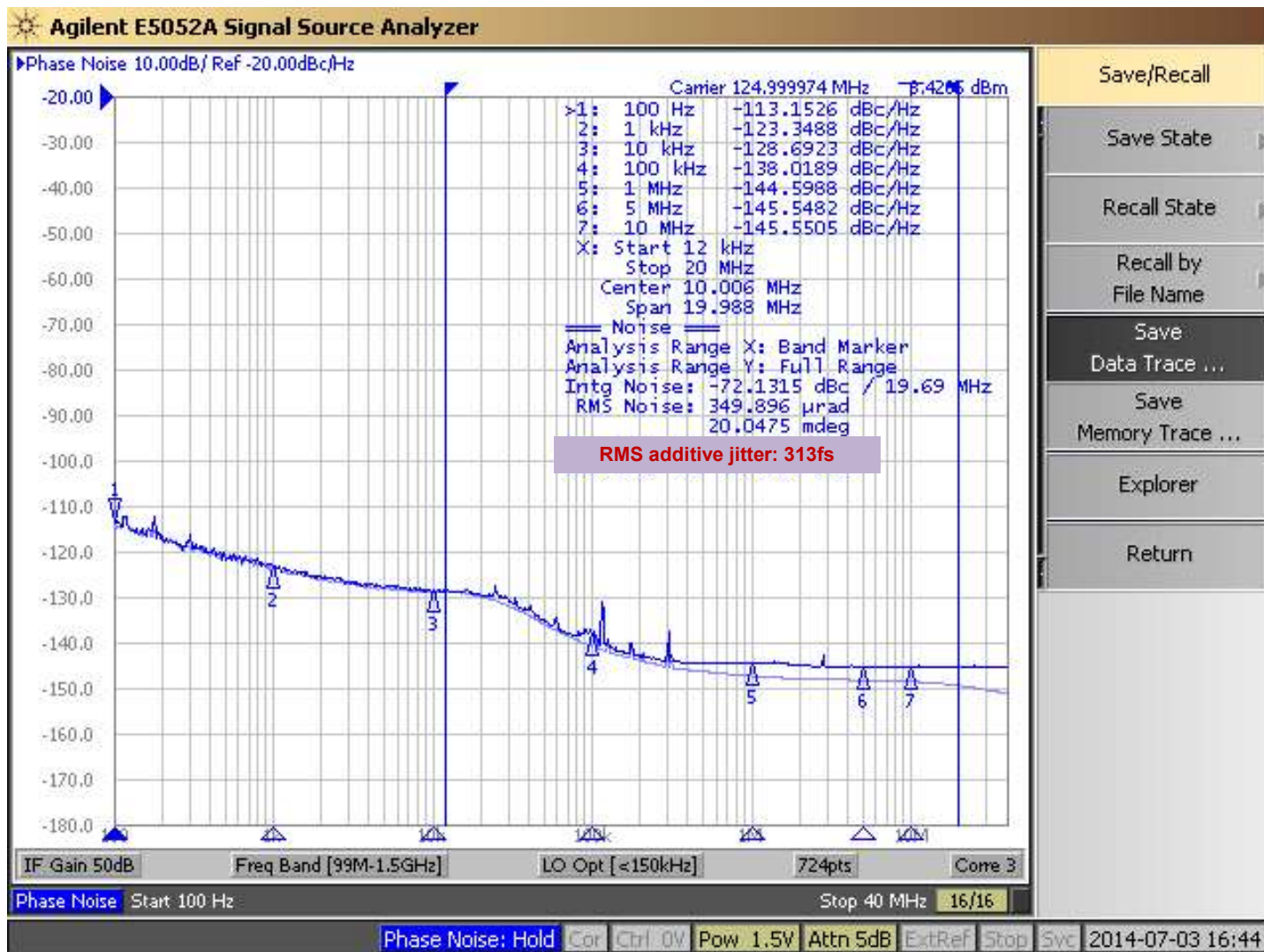
<sup>4</sup> For RMS figures, additive jitter is calculated by solving the following equation: Additive jitter = SQRT[(total jitter)<sup>2</sup> - (input jitter)<sup>2</sup>]

<sup>5</sup> Driven by 9FGU0831 or equivalent

<sup>6</sup> Rohde&Schartz SMA100



## Additive Phase Jitter Plot: 125M (12kHz to 20MHz)



## General SMBus Serial Interface Information

### How to Write

- Controller (host) sends a start bit
- Controller (host) sends the write address
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) sends the byte count = X
- IDT clock will **acknowledge**
- Controller (host) starts sending Byte N through Byte N+X-1
- IDT clock will **acknowledge** each byte **one at a time**
- Controller (host) sends a Stop bit

Index Block Write Operation			
Controller (Host)			IDT (Slave/Receiver)
T	starT bit		
Slave Address			
WR	WRite		
			ACK
Beginning Byte = N			
			ACK
Data Byte Count = X			
			ACK
Beginning Byte N		X Byte	
			ACK
O			O
O			O
O			O
Byte N + X - 1			
			ACK
P	stoP bit		

**Note: SMBus Address is Latched on SADR pin.**

### How to Read

- Controller (host) will send a start bit
- Controller (host) sends the write address
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) will send a separate start bit
- Controller (host) sends the read address
- IDT clock will **acknowledge**
- IDT clock will send the data byte count = X
- IDT clock sends Byte N+X-1
- IDT clock sends **Byte 0 through Byte X (if X<sub>(H)</sub> was written to Byte 8)**
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

Index Block Read Operation			
Controller (Host)			IDT (Slave/Receiver)
T	starT bit		
Slave Address			
WR	WRite		
			ACK
Beginning Byte = N			
			ACK
RT	Repeat starT		
Slave Address			
RD	ReaD		
			ACK
			Data Byte Count=X
ACK		X Byte	
ACK			Beginning Byte N
			O
			O
			O
			Byte N + X - 1
N	Not acknowledge		
P	stoP bit		

**SMBus Table: Output Enable Register <sup>1</sup>**

Byte 0	Name	Control Function	Type	0	1	Default
Bit 7	DIF OE5	Output Enable	RW	Low/Low	Enabled	1
Bit 6	DIF OE4	Output Enable	RW	Low/Low	Enabled	1
Bit 5	Reserved					1
Bit 4	DIF OE3	Output Enable	RW	Low/Low	Enabled	1
Bit 3	DIF OE2	Output Enable	RW	Low/Low	Enabled	1
Bit 2	DIF OE1	Output Enable	RW	Low/Low	Enabled	1
Bit 1	Reserved					1
Bit 0	DIF OE0	Output Enable	RW	Low/Low	Enabled	1

1. A low on these bits will override the OE# pin and force the differential output Low/Low

**SMBus Table: PLL Operating Mode and Output Amplitude Control Register**

Byte 1	Name	Control Function	Type	0	1	Default
Bit 7	PLLMODERB1	PLL Mode Readback Bit 1	R	See PLL Operating Mode Table		Latch
Bit 6	PLLMODERB0	PLL Mode Readback Bit 0	R			Latch
Bit 5	PLLMODE_SWCNTRL	Enable SW control of PLL Mode:	RW	Values in B1[7:6] set PLL Mode	Values in B1[4:3] set PLL Mode	0
Bit 4	PLLMODE1	PLL Mode Control Bit 1	RW <sup>1</sup>	See PLL Operating Mode Table		0
Bit 3	PLLMODE0	PLL Mode Control Bit 0	RW <sup>1</sup>			0
Bit 2	Reserved					1
Bit 1	AMPLITUDE 1	Controls Output Amplitude	RW	00 = 0.55V	01 = 0.65V	1
Bit 0	AMPLITUDE 0		RW	10 = 0.7V	11 = 0.8V	0

1. B1[5] must be set to a 1 for these bits to have any effect on the part.

**SMBus Table: DIF Slew Rate Control Register**

Byte 2	Name	Control Function	Type	0	1	Default
Bit 7	SLEWRATESEL DIF5	Adjust Slew Rate of DIF5	RW	Slow Setting	Fast Setting	1
Bit 6	SLEWRATESEL DIF4	Adjust Slew Rate of DIF4	RW	Slow Setting	Fast Setting	1
Bit 5	Reserved					1
Bit 4	SLEWRATESEL DIF3	Adjust Slew Rate of DIF3	RW	Slow Setting	Fast Setting	1
Bit 3	SLEWRATESEL DIF2	Adjust Slew Rate of DIF2	RW	Slow Setting	Fast Setting	1
Bit 2	SLEWRATESEL DIF1	Adjust Slew Rate of DIF1	RW	Slow Setting	Fast Setting	1
Bit 1	Reserved					1
Bit 0	SLEWRATESEL DIF0	Adjust Slew Rate of DIF0	RW	Slow Setting	Fast Setting	1

Note: See "Low-Power HCSL Outputs" table for slew rates.

**SMBus Table: Frequency Select Control Register**

Byte 3	Name	Control Function	Type	0	1	Default
Bit 7	Reserved					1
Bit 6	Reserved					1
Bit 5	Reserved					0
Bit 4	Reserved					0
Bit 3	Reserved					0
Bit 2	Reserved					1
Bit 1	Reserved					1
Bit 0	SLEWRATESEL FB	Adjust Slew Rate of FB	RW	Slow Setting	Fast Setting	1

Byte 4 is Reserved and reads back 'hFF'

**SMBus Table: Revision and Vendor ID Register**

Byte 5	Name	Control Function	Type	0	1	Default
Bit 7	RID3	Revision ID	R	A rev = 0000		0
Bit 6	RID2		R			0
Bit 5	RID1		R			0
Bit 4	RID0		R			0
Bit 3	VID3	VENDOR ID	R	0001 = IDT		0
Bit 2	VID2		R			0
Bit 1	VID1		R			0
Bit 0	VID0		R			1

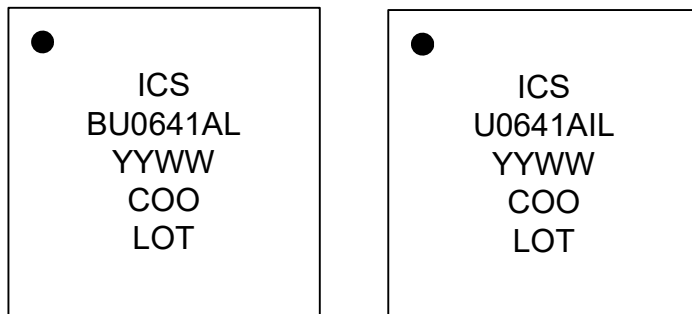
**SMBus Table: Device Type/Device ID**

Byte 6	Name	Control Function	Type	0	1	Default
Bit 7	Device Type1	Device Type	R	00 = FGx, 01 = DBx ZDB/FOB, 10 = DMx, 11= DBx FOB		0
Bit 6	Device Type0		R			1
Bit 5	Device ID5	Device ID	R	000110 binary or 06 hex		0
Bit 4	Device ID4		R			0
Bit 3	Device ID3		R			0
Bit 2	Device ID2		R			1
Bit 1	Device ID1		R			1
Bit 0	Device ID0		R			0

**SMBus Table: Byte Count Register**

Byte 7	Name	Control Function	Type	0	1	Default
Bit 7	Reserved					0
Bit 6	Reserved					0
Bit 5	Reserved					0
Bit 4	BC4	Byte Count Programming	RW	Writing to this register will configure how many bytes will be read back, default is = 8 bytes.		0
Bit 3	BC3		RW			1
Bit 2	BC2		RW			0
Bit 1	BC1		RW			0
Bit 0	BC0		RW			0

## Marking Diagrams



### Notes:

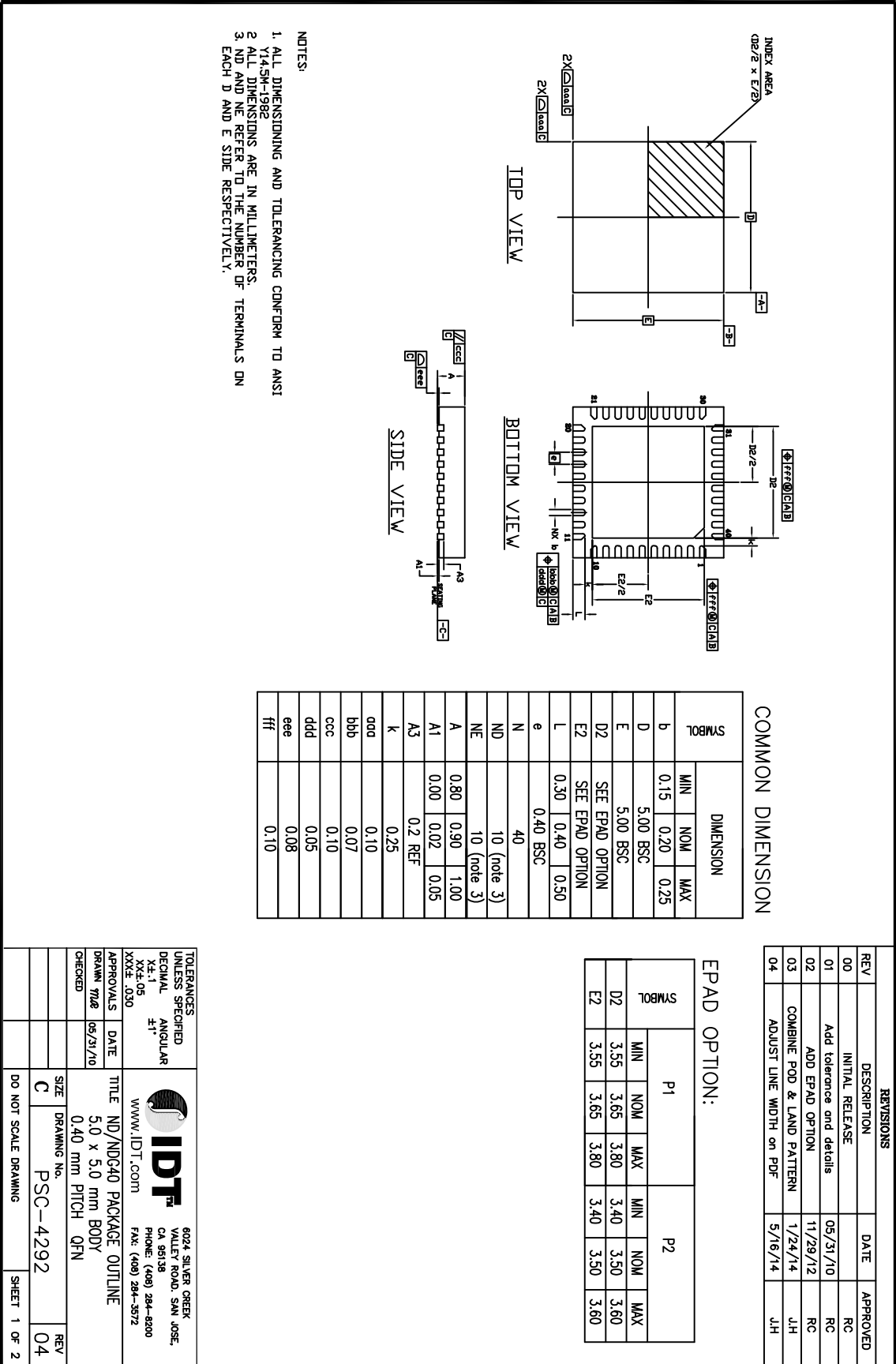
1. "LOT" is the lot sequence number.
2. "COO" denotes country of origin.
3. YYWW is the last two digits of the year and week that the part was assembled.
4. Line 2: truncated part number
5. "L" denotes RoHS compliant package.
6. "I" denotes industrial temperature range device.

## Thermal Characteristics

PARAMETER	SYMBOL	CONDITIONS	PKG	TYP VALUE	UNITS	NOTES
Thermal Resistance	$\theta_{JC}$	Junction to Case	NDG40	42	°C/W	1
	$\theta_{Jb}$	Junction to Base		2.4	°C/W	1
	$\theta_{JA0}$	Junction to Air, still air		39	°C/W	1
	$\theta_{JA1}$	Junction to Air, 1 m/s air flow		33	°C/W	1
	$\theta_{JA3}$	Junction to Air, 3 m/s air flow		28	°C/W	1
	$\theta_{JA5}$	Junction to Air, 5 m/s air flow		27	°C/W	1

<sup>1</sup>ePad soldered to board

# Package Outline and Package Dimensions (NDG40) – use EPAD Option P1



- NOTES:
1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5-1994
  2. ALL DIMENSIONS ARE IN MILLIMETERS.
  3. P1D AND N1E REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.

### COMMON DIMENSION

SYMBOL	DIMENSION		
	MIN	NOM	MAX
b	0.15	0.20	0.25
D	5.00 BSC		
E	5.00 BSC		
D2	SEE EPAD OPTION		
E2	SEE EPAD OPTION		
L	0.30	0.40	0.50
e	0.40 BSC		
N	40		
ND	10 (note 3)		
NE	10 (note 3)		
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	0.2 REF		
k	0.25		
ooo	0.10		
bbb	0.07		
ccc	0.10		
ddd	0.05		
eee	0.08		
fff	0.10		

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE		RC
01	Add tolerance and details	05/31/10	RC
02	ADD EPAD OPTION	11/29/12	RC
03	COMBINE P1D & LAND PATTERN	1/24/14	JH
04	ADJUST LINE WIDTH on PDF	5/16/14	JH

### EPAD OPTION:

SYMBOL	P1			P2		
	MIN	NOM	MAX	MIN	NOM	MAX
D2	3.55	3.65	3.80	3.40	3.50	3.60
E2	3.55	3.65	3.80	3.40	3.50	3.60

**TOLERANCES**  
UNLESS SPECIFIED

DECIMAL  
XX±.05

ANGULAR  
±1°

XXX±.030

APPROVALS  
DRAWN 7/02 06/21/10

CHECKED

www.IDT.com

**IDT**

6024 SILVER CREEK  
VALLEY ROAD, SAN JOSE,  
CA 95138  
PHONE: (408) 284-8200  
FAX: (408) 284-3572

TITLE ND/NDG40 PACKAGE OUTLINE  
5.0 x 5.0 mm BODY  
0.40 mm PITCH QFN

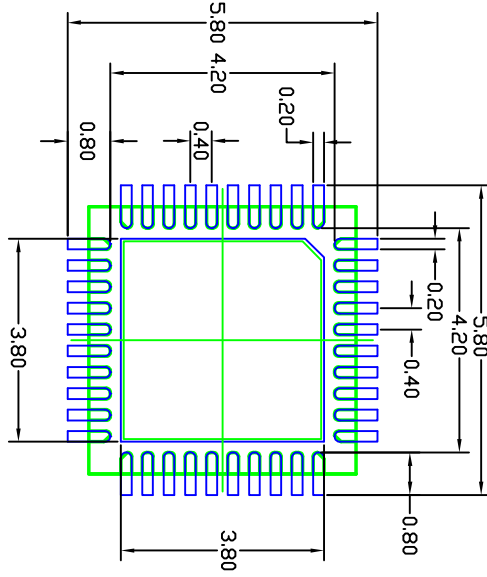
SIZE C DRAWING No. PSC-4292

DO NOT SCALE DRAWING

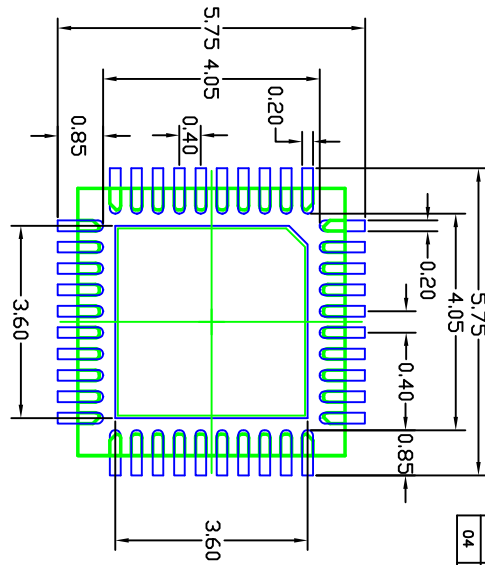
REV 04

SHEET 1 OF 2

Package Outline and Package Dimensions (NDG40) – use EPAD 3.65 mm SQ



EPAD 3.65 mm SQ



EPAD 3.50 mm SQ

- NOTES:
1. ALL DIMENSION ARE IN mm. ANGLES IN DEGREES.
  2. TOP DOWN VIEW, AS VIEWED ON PCB.
  3. COMPONENT OUTLINE SHOW FOR REFERENCE IN GREEN.
  4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
  5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE		RC
01	Add tolerance and details	05/31/10	RC
02	ADD EPAD OPTION	11/29/12	RC
03	COMBINE POD & LAND PATTERN	1/24/14	JH
04	ADJUST LINE WIDTH on PDF	5/16/14	JH

TOLERANCES UNLESS SPECIFIED		www.IDT.com	
DECIMAL	±0.1	6024 SILVER CREEK VALLET ROAD, SAN JOSE, CA 95135	
ANGULAR	±1°	PHONE (408) 294-6200	
XXX.X	0.30	FAX (408) 294-3572	
APPROVALS	DATE	TITLE	
DRAWN 7/02	05/31/10	ND/NDG40 PACKAGE OUTLINE	
CHECKED		5.0 x 5.0 mm BODY	
		0.40 mm PITCH QFN	
SIZE	DRAWING No.	REV	
C	PSC-4292	04	
DO NOT SCALE DRAWING			SHEET 2 OF 2

## Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature
9DBU0641AKLF	Trays	40-pin VFQFPN	0 to +70° C
9DBU0641AKLFT	Tape and Reel	40-pin VFQFPN	0 to +70° C
9DBU0641AKILF	Trays	40-pin VFQFPN	-40 to +85° C
9DBU0641AKILFT	Tape and Reel	40-pin VFQFPN	-40 to +85° C

"LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

"A" is the device revision designator (will not correlate with the datasheet revision).

## Revision History

Rev.	Initiator	Issue Date	Description	Page #
A	RDW	7/15/2014	<ol style="list-style-type: none"> <li>Updated electrical tables with char data.</li> <li>Added an additive phase jitter plot.</li> <li>Added 12kHz to 20MHz <i>additive</i> phase jitter spec.</li> <li>Updated Amplitude control bit <i>descriptions</i> in Byte 1.</li> </ol>	Various
B	RDW	9/19/2014	Updated SMBus Input High/Low parameters conditions, MAX values, and footnotes.	6
C	RDW	4/22/2015	<ol style="list-style-type: none"> <li>Updated pin out and pin descriptions to show ePad on package connected to ground.</li> <li>Minor updates to front page text for family consistency.</li> <li>Updated Clock Input Parameters table to be consistent with PCIe Vswing parameter.</li> </ol>	1,5





## IMPORTANT NOTICE AND DISCLAIMER

RENESAS ELECTRONICS CORPORATION AND ITS SUBSIDIARIES (“RENESAS”) PROVIDES TECHNICAL SPECIFICATIONS AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS OR IMPLIED, INCLUDING, WITHOUT LIMITATION, ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT OF THIRD-PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for developers who are designing with Renesas products. You are solely responsible for (1) selecting the appropriate products for your application, (2) designing, validating, and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. Renesas grants you permission to use these resources only to develop an application that uses Renesas products. Other reproduction or use of these resources is strictly prohibited. No license is granted to any other Renesas intellectual property or to any third-party intellectual property. Renesas disclaims responsibility for, and you will fully indemnify Renesas and its representatives against, any claims, damages, costs, losses, or liabilities arising from your use of these resources. Renesas' products are provided only subject to Renesas' Terms and Conditions of Sale or other applicable terms agreed to in writing. No use of any Renesas resources expands or otherwise alters any applicable warranties or warranty disclaimers for these products.

(Disclaimer Rev.1.01 Jan 2024)

### Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,  
Koto-ku, Tokyo 135-0061, Japan  
[www.renesas.com](http://www.renesas.com)

### Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

### Contact Information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit [www.renesas.com/contact-us/](http://www.renesas.com/contact-us/).